



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-08-10
Contact Name *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Representative Title	ADG MD Champion
Authorized Representative *	Rossana Bonaccorso	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	S0M5*XV71ABT	A	3068	2018-08-10
Amount	UoM	Unit type	ST ECOPACK Grade	
150.00	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	3.9-4.9-1.55	16	gull wing	
Comment	Package: POWERSO 16 LEADS EP DIP DOWNSET - MDF valid for CPs: VND7E025AJTR and VND7E025AJ			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.03	die	173
Lead	3.77	soft solder	25113

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	3.77	soft solder	25113
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	3.77	soft solder	954880

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	S0M5*XV71ABT					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.357	mg	supplier	die	Silicon (Si)	7440-21-3		1.094	mg	806190	7293
				supplier	metallization	Aluminium (Al)	7429-90-5		0.083	mg	61164	553
				supplier	metallization	Copper (Cu)	7440-50-8		0.030	mg	22108	200
				supplier	metallization	Titanium (Ti)	7440-32-6		0.007	mg	5158	47
				supplier	Passivation	Silicon Oxide	7631-86-9		0.048	mg	35372	320
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	1474	13
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.026	mg	19160	173
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.002	mg	1474	13
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.011	mg	8106	73
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.054	mg	39794	360
Leadframe	M-004 Copper and its alloys	70.071	mg	supplier	alloy	Copper (Cu)	7440-50-8		69.250	mg	988283	461662
				supplier	alloy	Iron (Fe)	7439-89-6		0.069	mg	985	460
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.021	mg	300	140
				supplier	metallization	Silver (Ag)	7440-22-4		0.731	mg	10432	4873
				supplier	metallization	Lead (Pb)	7439-92-1	7a-Lead in high met	3.767	mg	954880	25113
Soft solder	Solder	3.945	mg	JIG - R	solder	Silver (Ag)	7440-22-4		0.099	mg	25095	660
				supplier	solder	Tin (Sn)	7440-31-5		0.079	mg	20025	527
				supplier	wire	Copper (Cu)	7440-50-8		0.434	mg	1000000	2893
Encapsulation	M-011 Other inorganic materials	72.897	mg	supplier	mold compound	Silica, vitreous	60676-86-0		62.982	mg	863986	419880
				supplier	mold compound	Epoxy Resin	25068-38-6		5.467	mg	74996	36447
				supplier	mold compound	Phenol Resin	29690-82-2		3.645	mg	50002	24300
				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		0.365	mg	5008	2433
				supplier	mold compound	Quartz	14808-60-7		0.219	mg	3004	1460
Connections coating	Solder	1.297	mg	supplier	mold compound	Carbon black	1333-86-4		0.219	mg	3004	1460
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.297	mg	1000000	8647